Product Disassembly Instructions

Product Category:

Panel PC

Product Marketing Name / Model:

PPC-6121

Purpose: The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq. cm Mother board, Card Reader board, USB Daughter board, LID Daughter board	7
Batteries	All types including standard alkaline and lithium coin or button style batteries 6cell battery or 9 cell battery, and RTC battery	1
External electrical cables and Power cord		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Gas Discharge Lamps		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0

Item Description	Notes	Quantity of items included in product
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Capacitors / condensers (Containing PCB)		0

Plastics containing Brominated Flame Retardants weighing > 25 grams	(Not including PCBs or PCAs already listed as a separate item above)	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Asbestos waste and components which contain asbestos		0
Components containing refractory ceramic fibers		0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC)		0
Components, parts and materials containing radioactive substances		0

2.0   Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

Disassembly Tool	Picture
Screwdriver	
Lever	
Star Screwdriver	
Hexagon Driver	
Slanted pliers	
Pliers	
Hammer	
Knife	

3.0   Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials.

A. Disassembly Box module.

A-1. Disassembly 5 pcs screw to remove the Rear cover.

A-2. Disassembly 2 pcs Antenna rubber.

A-3. Disassembly 1 pcs screw to remove the Riser card bracket.

A-4. Disassembly 6 pcs screw to remove the VESA bracket module.

A-5. Disassembly 8 pcs screw to remove the FAN.

A-6. Disassembly 4 pcs screw to remove the CPU cooler.

A-7. Disassembly 4 pcs screw to remove the HDD/SSD module

A-8. Disassembly 4 pcs screw to remove the HDD/SSD tray

A-9. Disassembly 4 pcs screw to remove the HDD/SSD

A-10. Disassembly Hex 12pcs from DB9/DB15 port, screw 4pcs from IO bracket to separate the IO bracket.

A-11. Disassembly Power button from IO bracket.

A-12. Disassembly 4 pcs screw to remove the Speaker module.

A-13. Disassembly CPU from CPU socket.

A-14. Disassembly DDR module from DDR socket.

A-15. Disassembly M.2 card (1pcs screw) and Mini PCIe card (2pcs screw) from each socket.

A-16. Remove RTC battery wire cable.

A-17. Disassembly 7 pcs screw to remove the Mother board.

B. Disassembly Panel module.

B-1. Disassembly 7 pcs screw to remove the MB frame.

B-2. Disassembly screw 4pcs to remove the LCD sub-assembly from Front Bezel.

B-3. Disassembly screw 4pcs to separate the LCD bracket left and right with LCD module.

B-4. Separate the LCD sponge from LCD opening bezel.

B-5. Disassembly screw 1pcs to remove the LED indicator board.

B-6. Remove the waterproof from front bezel.

3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).